



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-03-09
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WBA52KGU6	72MG*492XXXB	A	998Z	2025-03-09
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	50	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	5x5	32	Flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	72MG*492XXB		49.8293		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.501	mg	supplier	die	Silicon (Si)	7440-21-3		2.256	mg	902164	45280.86
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	10985	551.35
				supplier	metallization	Copper (Cu)	7440-50-8		0.081	mg	32269	1619.63
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.014	mg	5493	275.70
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	1373	68.91
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	343	17.22
				supplier	Passivation	Silicon Nitride	12033-89-5		0.019	mg	7552	379.05
				supplier	Passivation	Silicon Oxide	7631-86-9		0.100	mg	39821	1998.67
				DAF (FH9011T)	Other Organic Materials	0.424	mg	supplier	Organic Compounds	Epoxy Resin	Proprietary	
supplier	Organic Compounds	Phenol Resin	Proprietary						0.060	mg	142180	1209.82
supplier	Organic Compounds	SiO2 Filler	Proprietary						0.022	mg	52133	443.60
supplier	Organic Compounds	(Meta)Acrylate Copolymer	Proprietary						0.281	mg	663507	5645.82
Encapsulation (EME-G770)	Other Organic Materials	15.809	mg	supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.332	mg	21000	6662.53
				supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.332	mg	21000	6662.53
				supplier	Organic Compounds	Phenol Resin A	Proprietary		0.332	mg	21000	6662.53
				supplier	Glass	Silica(Amorphous)A	60676-86-0		12.338	mg	780450	247608.17
				supplier	Glass	Silica(Amorphous)B	7631-86-9		1.823	mg	115320	36586.81
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.098	mg	6230	1976.55
				supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.221	mg	14000	4441.69
Bonding Wire (Au)	Bonding Wire	0.376	mg	supplier	Organic Compounds	Phenol Resin B	Proprietary		0.332	mg	21000	6662.53
				supplier	Metals	Gold	7440-57-5		0.376	mg	1000000	7552.56
Plating (Sn)	Other inorganic materials	0.719	mg	supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14427.86
Leadframe (C7025 + Ag)	Copper & its alloys	30.000	mg	supplier	Metals	Copper	7440-50-8		28.725	mg	957500	576468.43
				supplier	Metals	Magnesium	7439-95-4		0.045	mg	1500	903.08
				supplier	Metals	Nickel	7440-02-0		0.894	mg	29800	17941.26
				supplier	Metals	Silicon	7440-21-3		0.195	mg	6500	3913.36
				supplier	Metals	Silver	7440-22-4		0.141	mg	4700	2829.66